



INITIAL PRODUCT/PROCESS CHANGE NOTIFICATION #16935Generic Copy

Issue Date: 27-Nov-2012

TITLE: Initial Notification of Qualification of ON Semiconductor Philippines Inc. for Assembly of 8 Lead TSSOP 4.4x3.0mm Packages.

PROPOSED FIRST SHIP DATE: 27-Mar-2013

AFFECTED CHANGE CATEGORY(S): ON Semiconductor Assembly

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:

Contact your local ON Semiconductor Sales Office or <Shao.Sia@onsemi.com>

NOTIFICATION TYPE:

Initial Product/Process Change Notification (IPCN)

First change notification sent to customers. IPCNs are issued at least 120 days prior to implementation of the change. An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan.

The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN).

This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change.

DESCRIPTION AND PURPOSE:

IPCN# 16935 is available at www.onsemi.com. This is to notify customers of the assembly site transfer of 8 Lead TSSOP8 4.4x3.0mm package. Historically, the device listed was being assembled at Amkor located in Laguna, Philippines. At the expiration of Initial and Final PCN, the device listed will be assembled at ON Semiconductor located in Cavite, Philippines. The change also includes MSL 1/260C qualification.

**Initial Product/Process Change Notification # 16935****QUALIFICATION PLAN:**

Test	Conditions
MSL 1 Preconditioning (PC)	3xIR @ 260 °C
Temp Cycling + preconditioning (TC+PC)	Temp= -65 °C to +150 °C; for 500 cycles
Autoclave + preconditioning (AC+PC)	Temp= +121 °C; RH=100%, 15 PSIG for 96 hours
High Temp Storage Life (HTSL)	Temp= +150 °C for 1,008 Hours
Scanning Acoustic Tomography (SAT)	ON Semiconductor SAT Guidelines
Wire Bond Shear Test (WBS)	Cpk>1.33
Wire Bond Pull Test (BPS)	Cpk>1.33
Solderability (SD)	>95% lead coverage
Physical Dimensions (PD)	Cpk>1.33

List of affected General Parts:

NB2305AI1DTG
NB2305AI1DTR2G
NB2305AI1HDTG
NB2305AI1HDTR2G
NB3N2304NZDTG
NB3N2304NZDTR2G